



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the application of:

Lynn Forester, et al

Docket: 30-3928 (4780) DIV-1

Serial Number: 10/726,154

Group Art Unit:

Filed: December 2, 2003

Examiner:

For: Electron-Beam Processed Films for Microelectronic Structures

DISCLOSURE UNDER 37 C.F.R. 1.56

Commissioner For Patents

P.O. Box 1450

Alexandria, Virginia 22313-1450

Sir:

Submitted herewith on Form PTO-1449 is a listing of documents known to Applicant in order to comply with Applicant's duty of disclosure pursuant to 37 C.F.R. 1.56. Copies of the documents are also being submitted herewith to comply with the provisions of 37 C.F.R. 1.97 and 1.98.

The submission of these documents is not intended as an admission that any or all of these materials are prior art against the claims of the present application. Applicant does not waive any rights to file Affidavits under 37 C.F.R. 1.131, to copy claims from the listed patent documents, or to take any other action which would be appropriate in the event that one or more of the documents are determined to be questionable as references against the claims of the present application.

None of these documents are believed to impair the patentability of the presently claimed invention. Nevertheless, to complete the record, formal consideration and citation of these documents is requested.

Respectfully submitted,

Richard S. Roberts

Reg. No. 27,941

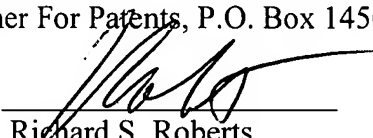
P.O. Box 484

Princeton, New Jersey 08542

(609) 921-3500

Date: February 9, 2004

I hereby certify that this document, including all attachments, is being deposited with the United States Postal Service "Express Mail-Post Office to Addressee" service under 37 C.F.R. 1.10 on the date indicated above in a postage paid envelope addressed to the Commissioner For Patents, P.O. Box 1450, Alexandria, Virginia 22313-1450.

  
\_\_\_\_\_  
Richard S. Roberts  
Reg. No. 27,941

**FORM PTO-1449 U.S. DEPARTMENT OF  
COMMERCE**  
(Rev. 2-32) **PATENT AND TRADEMARK OFFICE**

ATTY. DOCKET NO:  
30-3928(4780)DIV-1

SERIAL NO.:  
10/726,154

INFORMATION DISCLOSURE  
STATEMENT BY APPLICANT

APPLICANT:  
LYNN FORESTER, ET AL

(Use several sheets if necessary)

FILING DATE:  
December 2, 2003

GROUP:

### U.S. PATENT DOCUMENTS

EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
	AA						
	AB						
	AC						
	AD						
	AE						
	AF						
	AG						
	AH						
	AI						
	AJ						
	AK						

### FOREIGN PATENT DOCUMENTS

							TRANSLATION	
		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	YES	NO
	AL	03-260073	11/20/1991	JAPAN				
	AM							
	AN							

### OTHER DOCUMENTS(Including Author, Title, Date, Pertinent Pages, etc.)

AO	Kern; "Deposited Dielectrics For VLSI", 8(7) Semiconductor International 122 (July 1995)
AP	Gurczyca et al.; "Plasma-Enhanced Chemical Deposition of Dielectric", 8(4), VLSI Electronics Microstructure Science (New York 1984)
AQ	Mattson; "CVD Films For Interlayer Dielectrics", Solid State Technology 60 (Jan. 1980)
AR	Loh et al.; "Modeling and measurement of Contact Resistances", IEEE Transactions Electron Devices, pp. 512-524, (March 1987)
AS	Andoh et al., "Design Methodology for Low Voltage MOFSETs", International Electron Device Meeting (IEDM) pp. 94-79 - 94-82, (Dec. 1994)
AT	Chen et al.; Tech. Digest, IEDM, pp. 484-487 (1986)
AU	Rountree, Tech. Digest, IEDM, pp. 580-583 (1988)

EXAMINER

DATE CONSIDERED

Examiner: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

<b>FORM PTO-1449 U.S. DEPARTMENT OF COMMERCE</b> (Rev. 2-32) <b>PATENT AND TRADEMARK OFFICE</b>				ATTY. DOCKET NO: 30-3928(4780)DIV-1		SERIAL NO.: 10/726,154	
INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use several sheets if necessary)				APPLICANT: LYNN FORESTER, ET AL			
FILING DATE: December 2, 2003				GROUP:			

U.S. PATENT DOCUMENTS							
EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE	
	AA						
	AB						
	AC						
	AD						
	AE						
	AF						
	AG						
	AH						
	AI						
	AJ						
	AK						

FOREIGN PATENT DOCUMENTS							TRANSLATION	
DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	YES	NO		
AL								
AM								
AN								

OTHER DOCUMENTS(Including Author, Title, Date, Pertinent Pages, etc.)	
AO	Shimizu et al., "O.15 $\mu$ CMOS Process For High Performance and High Reliability", IEDM, pp. 94-67 – 94-70 (Dec. 1994)
AP	Kojima et al.; "Planarization Process Using A Multi-Coating of Spin-On-Glass", VMIC, pp. 390-396 (June 1988)
AQ	Forester et al.; "Electron Beam Curing of Non-Etchback SOG and Application To A 0.5 $\mu$ m CMOS SRAM Process"; VMIC Conference pp. 83-89 (June 27, 1995)
AR	"Spin/Bake/Cure Procedure for Spin-On Glass Materials For Interlevel Dielectric Planarization", AlliedSignal Inc. (1994)
AS	Takeishi et al.; "Stabilizing Dielectric Constants of Fluorine-Doped-SiO <sub>2</sub> Films by N <sub>2</sub> O Plasma Annealing", DUMIC Conference, pp. 257-259 (Feb. 1995)
AT	Electron Vision Technical Bulletin, "Electron Beam Processing of AlliedSignal Accuglass 211 SOG", (June 1994)
AU	

EXAMINER	DATE CONSIDERED
Examiner: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.	